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PATENT
Attorney Docket No.: SAM-0313

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Soo-geun Lee, *et al.*

Serial No.: 10/081,661

Filing Date: February 22, 2002

Title: METHOD OF MANUFACTURING INTERCONNECTION LINE IN
SEMICONDUCTOR DEVICE

Examiner: Nguyen, H.

Group Art Unit: 2812

2/5/03
Smith

CERTIFICATE OF MAILING UNDER 37 C.F.R. § 1.8

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January 24, 2003
Date

Lisa Sanders
Lisa Sanders

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BOX NON-FEE AMENDMENT
Assistant Commissioner for Patents
Washington, D.C. 20231

AMENDMENT A

Sir:

This is in response to the Office Action mailed on October 24, 2002.

Please amend the application as follows:

In the Claims

Please amend the claims as follows:

1. (Amended) A method of forming an interconnection line in a semiconductor device comprising:

forming a first etching stopper on a lower conductive layer which is formed on a semiconductor substrate;

forming a first interlayer insulating layer on the first etching stopper;

forming a second etching stopper on the first interlayer insulating layer;

forming a second interlayer insulating layer on the second etching stopper;